



ABSTRACT

This report presents the reliability and qualification results for the LMX1860-SEP radiation tolerant low-noise, high-frequency JESD204B/C buffer, multiplier and divider in Space Enhanced Plastic (SEP). The LMX1860-SEP is manufactured with a controlled baseline that has the following:

- An extended product life cycle
 - One assembly and test site
 - Product traceability
 - Radiation lot acceptance testing
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1 Texas Instruments Enhanced Product Qualification and Reliability Report

TI qualification testing is a risk mitigation process that is engineered to verify device longevity in customer applications. Wafer fabrication process and package level reliability are evaluated in a variety of ways that can include accelerated environmental test conditions with subsequent derating to actual use conditions. Manufacturability of the device is evaluated to verify a robust assembly flow and maintain continuity of supply to customers. TI Enhanced Products are qualified with industry standard test methodologies performed to the intent of Joint Electron Devices Engineering Council (JEDEC) standards and procedures. Texas Instruments Enhanced Products are certified to meet GEIA-STD-0002-1 Aerospace Qualified Electronic Components.

2 Space-Enhanced Plastic Production Flow

2.1 Device Introduction

The LMX1860-SEP is a radiation-hardened device in a plastic package which allows these devices to be used in space applications. The device was verified immune to $43\text{MeV} \times \text{cm}^2 / \text{mg}$ at 125°C for Single-Event Latch-up (SEL) and Single-Event Functional Interrupt (SEFI). Each fabrication lot was tested according to MIL-STD-883 for Radiation Lot Acceptance Tested (RLAT) up to 30 krad(Si) and each assembly and test lot follows the process flow shown in [Figure 2-1](#). To verify the quality of the LMX1860-SEP, the device is qualified with Space EP requirements. See [Section 3](#) for further details.

2.2 LMX1860-SEP Space-Enhanced Plastic Production Flow

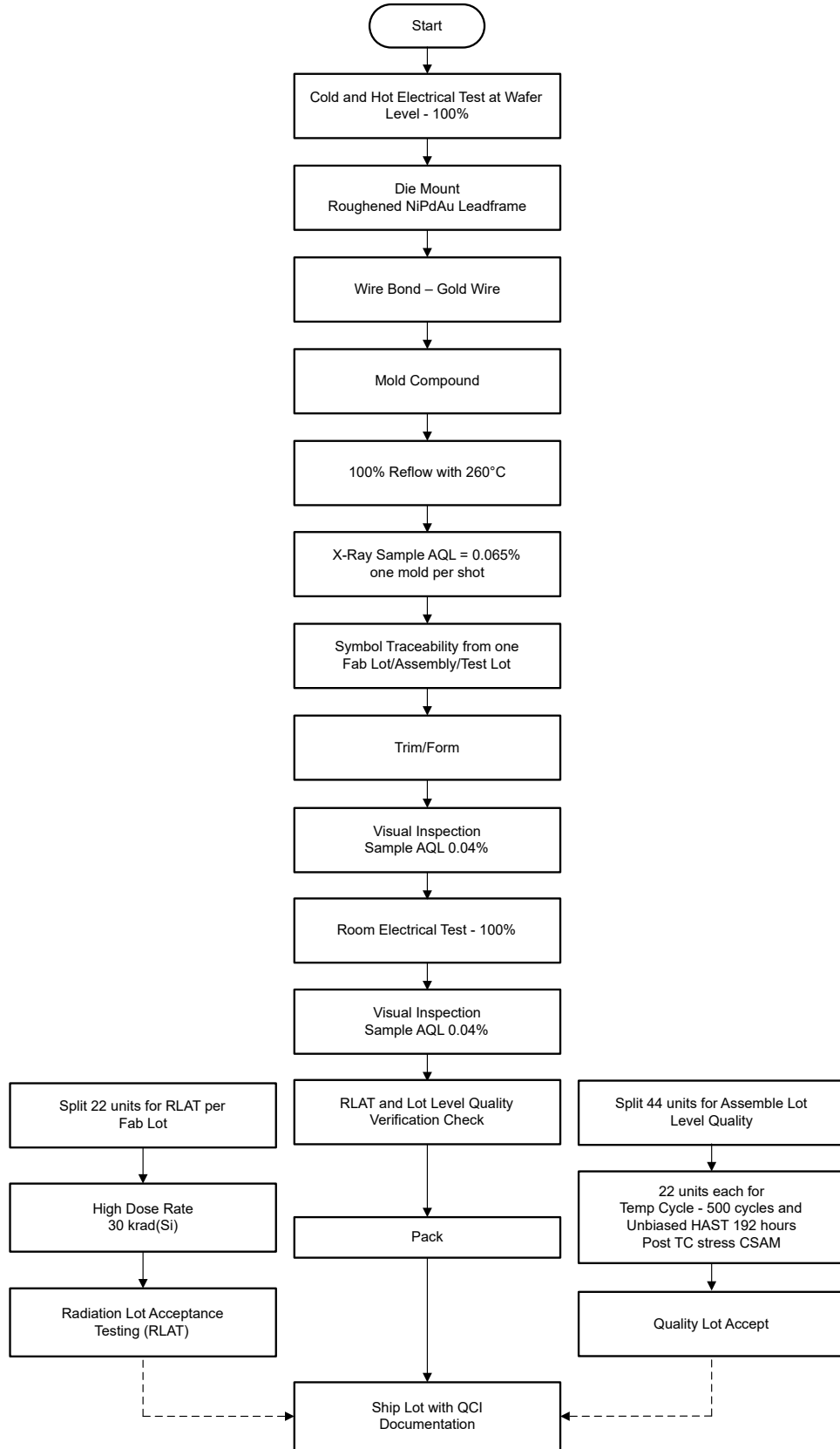


Figure 2-1. LMX1860-SEP Space-Enhanced Plastic Production Flow Chart

3 Device Qualification

The following is the device qualification summary.

Qualification by Similarity (Qualification Family)

A new device can be qualified either by performing full scale quality and reliability tests on the actual device or using previously qualified devices through "Qualification by Similarity" (QBS) rules. By establishing similarity between the new device and those qualified previously, repetitive tests are eliminated, allowing for timely production release. When adopting QBS methodology, the emphasis is on qualifying the differences between a previously qualified product and the new product under consideration.

The QBS rules for a technology, product, test parameters or package shall define which attributes are required to remain fixed in order for the QBS rules to apply. The attributes which are expected and allowed to vary are reviewed and a QBS plan shall be developed, based on the reliability impact assessment above, specifying what subset of the full complement of environmental stresses is required to evaluate the reliability impact of those variations. Each new device shall be reviewed for conformance to the QBS rule sets applicable to that device. See JEDEC JESD47 for more information.

Table 3-1. Space Enhanced Products New Device Qualification Matrix

DESCRIPTION	CONDITION	SAMPLE SIZE USED/ REJECTS	LOTS REQUIRED	TEST METHOD
Note that qualification by similarity ("qualification family") per JEDEC JESD47 is allowed.				
Electromigration	Maximum Recommended Operating Conditions	N/A	N/A	Per TI Design Rules
Wire Bond Life	Maximum Recommended Operating Conditions	N/A	N/A	Per TI Design Rules
Electrical Characterization	TI Data Sheet	10	3	N/A
Electrostatic Discharge Sensitivity	HBM per TI Data sheet	3 units/voltage	1	JEDEC JS-001 or EIA/JESD22-A114
	CDM per TI Data sheet			JEDEC JS-002 or EIA/JESD22-C101
Latch-up	Per Technology	3/0	1	EIA/JESD78
Physical Dimensions	TI Data Sheet	5/0	1	EIA/JESD22- B100
Thermal Impedance	Theta-JA on board	Per Pin-Package	N/A	EIA/JESD51
Bias Life Test	125°C / 1000 hours or equivalent	77/0	3	JESD22-A108*
Biased HAST	130°C / 85% / 96 hours or 110°C / 85% / 264 hours or 85°C / 85% / 1000 hours	77/0	3	JESD22-A110/A101*
Extended Biased HAST	130°C / 85% / 192 hours (for reference) Or 110°C / 85% /528 hours or 85°C / 85% / 2000 hours	77/0	1	JESD22-A110/A101*
Unbiased HAST	130°C / 85% / 96 hours or equivalent	77/0	3	JESD22-A.118*
Temperature Cycle	-65°C to +150°C non-biased 500 cycles or equivalent	77/0	3	JESD22-A104*
Solder Heat	260°C for 10 seconds	22/0	1	JESD22-B106

Table 3-1. Space Enhanced Products New Device Qualification Matrix (continued)

DESCRIPTION	CONDITION	SAMPLE SIZE USED/ REJECTS	LOTS REQUIRED	TEST METHOD
Resistance to Solvents	Ink symbol only	12/0	1	JESD22-B107
Solderability	Bake Preconditioning	22/0	1	ANSI/J-STD-002
Flammability	Method A / Method B	5/0	1	UL-1964
Bond Shear	Per wire size	5 units x 30/0 bonds	3	JESD22-B116
Bond Pull Strength	Per wire size	5 units x 30/0 bonds	3	ASTM F-459
Die Shear	Per die size	5/0	3	MIL-STD-883, TM 2019
High Temp Storage	150 °C / 1,000 hours	15/0	3	JESD22-A103*
Moisture Sensitivity	Surface Mount Only	12	1	J-STD-020*
Radiation Response Characterization	Per TI Data sheet	5 units/dose level	1	MIL-STD-883/Method 1019
Outgassing Characterization	TML <=1% (Total Mass Lost) CVCM <=0.1% (Collected Volatile Condensable Material)	5	1	ASTM E595

*Precondition performed per JEDEC Std. 22, Method A112/A113.

4 Outgas Test Report

The outgassing test was performed on 5 units. A total mass loss (TML) of 1.00% and collected volatile condensable material (CVCM) of 0.1% were used as screening levels for rejection of spacecraft materials. The outgas test was performed in a vacuum environment of less than 5×10^{-5} Torr, according to ASTM E 595, for a duration of 24 hours, at 125°C. The TML and CVCM were measured after the test.

Table 4-1. Outgas Test Results

SAMPLE	TML < 1.0%	CVCM < 0.1%
LMK04832MPAPSEP	PASS	PASS

5 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision * (May 2024) to Revision A (July 2024)

Page

- Added clarification to the test methods in the *Space Enhanced Products New Device Qualification Matrix* table.....4

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